

**IN THE SPECIFICATION:**

**Paragraph beginning at line 22 of page 2 has been amended as follows:**

Therefore, a reflow soldering process is currently employed, ~~ay by~~ applying a solder cream or the like in the location on the circuit board to be soldered and placing the component to be attached on that, or else providing a small solder ball to a part of the circuit board to be soldered after a component is placed on the circuit board, and then passing the circuit board, bearing the component thereon, through an oven of such a high temperature that the part to be soldered assumes a temperature equal to or higher than the melting point of solder, for example 200 to 260°C, thereby melting the solder and achieving the soldering operation.

**Paragraph beginning at line 13 of page 5 has been amended as follows:**

Fig. 1 is a lateral view of an ~~electrochemical~~ electrochemical cell of the present invention;

Paragraph beginning at line 20 of page 5 has been amended as follows:

An electrochemical cell of the present invention is mounted on a circuit board by soldering one electrode can directly to the circuit board and by connecting a terminal to the other electrode can only. Fig. 1 is a schematic lateral view showing a state where a terminal is connected to a positive pole can. The electrochemical cell of the present embodiment is formed by hermetically sealing a positive pole can 103 and a negative pole can 105 with a gasket 108 in between, and connecting a positive pole terminal 104 to the positive pole can 103. The can and the terminal are fixedly attached by laser welding at a laser weld point 101.